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 [ ] Other:

EXECUTION DATE: January 31, 2001, January 26, 2001 and January 29, 2001, respectively

Name of conveying Party(ies):

Masaru TAKAMATSU  
 Takashi KATAKURA  
 Toshiaki IWAMATSU  
 Hideki NARUOKA

Execution Date (M / D / Y):

January 31, 2001  
 January 26, 2001  
 January 26, 2001  
 January 29, 2001

Name of receiving Party(ies):

Mitsubishi Materials Silicon Corporation and  
 Mitsubishi Denki Kabushiki Kaisha

Address of receiving Party(ies):

5-1, Ohtemachi 1-chome, Chiyoda-ku, Tokyo 100-0004 JAPAN  
 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310 JAPAN

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Correspondence and/or Domestic Representative Name, Address and Phone No.:

Jules E. Goldberg, Esq., Reed Smith LLP, 375 Park Avenue, New York, NY 10152 [Tel. No. (212)521-5400]

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09/786228

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/ Ruth Montalvo

PATENT  
 REEL: 011638 FRAME: 0381

# ASSIGNMENT - PATENT APPLICATION

UNITED STATES OF AMERICA

1 of 2

Whereas, I/We, Masaru Takamatsu and Takashi Katakura

of c/o MITSUBISHI MATERIALS SILICON CORPORATION, 5-1, Ohtemachi 1-chome,  
Chiyoda-ku, Tokyo 100-0004 Japan

(hereafter "Assignor") have new and useful improvements in SOI SBSTRATE, MANUFACTURING METHOD  
THEREFOR, AND SEMICONDUCTOR DEVICE ADOPTING SOI SUBSTRATE

which application for Letters Patent in the United States of America | X is about to be filed. | | has been filed.

And Whereas, MITSUBISHI MATERIALS SILICON CORPORATION and  
MITSUBISHI DENKI KABUSHIKI KAISHA  
of 5-1, Ohtemachi 1-chome, Chiyoda-ku, Tokyo 100-0004 Japan  
2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310 Japan

(hereinafter "Assignee") is/are desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these presents does assign, transfer and set over unto the said Assignee for the territory of the United States of America, the full and exclusive right, title, and interest in and to the said application and the invention embodied therein, as fully set forth and described in the specification.

A. prepared and executed on even dates herewith

B. filed in the U.S. Patent and Trademark Office under Serial No. \_\_\_\_\_

on \_\_\_\_\_ including any division, continuation, substitute or renewal application thereof, said invention, application and Letters Patent to be held and enjoyed by the said Assignee to the full end of the term for which said Letters Patent is granted, as fully and entirely as the same would have been held by the Assignor had this assignment and transfer not been made.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 29th day of  
January 20 01.

WITNESS:

INVENTOR(S):

Masaru Takamatsu

(Name of Assignor)

Masaru Takamatsu 01/31/01  
(Signature of Assignor)

Takashi Katakura

(Name of Assignor)

Takashi Katakura 01/26/01  
(Signature of Assignor)

(Name of Assignor)

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**PATENT**  
**REEL: 011638 FRAME: 0382**

# ASSIGNMENT - PATENT APPLICATION

2 of 2

## UNITED STATES OF AMERICA

Whereas, I/We, Toshiaki Iwamatsu and Hideki Naruoka

of c/o MITSUBISHI DENKI KABUSHIKI KAISHA, 2-3, Marunouchi 2-chome,  
Chiyoda-ku, Tokyo 100-8310 Japan

(hereafter "Assignor") have new and useful improvements in SOI SUBSTRATE, MANUFACTURING METHOD  
THEREFOR, AND SEMICONDUCTOR DEVICE ADOPTING SOI SUBSTRATE

which application for Letters Patent in the United States of America ☒ is about to be filed. ☐ has been filed.

mitsubishi materials silicon corporation and

And Whereas, mitsubishi denki kabushiki kaisha  
of 5-1, Ohtemachi 1-chome, Chiyoda-ku, Tokyo 100-0004 Japan  
2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310 Japan

(hereinafter "Assignee") is/are desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

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In testimony whereof, the Assignor has hereunto set his hand this 29th day of  
January 20 01.

WITNESS:

INVENTOR(S):

Toshiaki Iwamatsu

(Name of Assignor)

Toshiaki Iwamatsu 01/26/01  
(Signature of Assignor)

Hideki Naruoka

(Name of Assignor)

Hideki Naruoka 01/29/01  
(Signature of Assignor)

\_\_\_\_\_  
(Name of Assignor)

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(Signature of Assignor)

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(Name of Assignor)

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(Signature of Assignor)

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RECORDED: 03/01/2001

PATENT  
REEL: 011638 FRAME: 0383